



# MPD TPC ASSEMBLING STATUS (10.09.2024)



## TPC:

- vessel assembly, ROC chambers, gating grid system

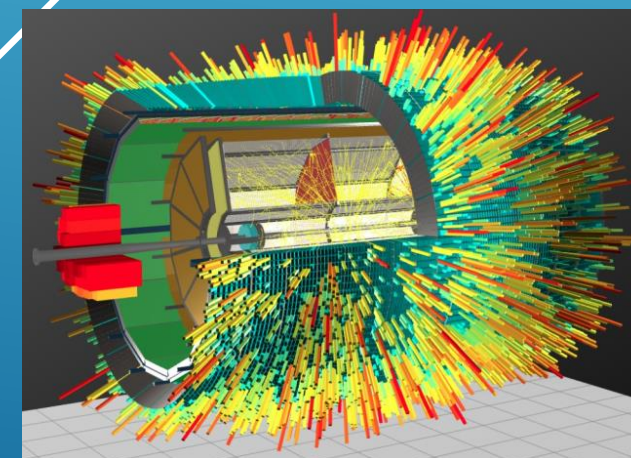
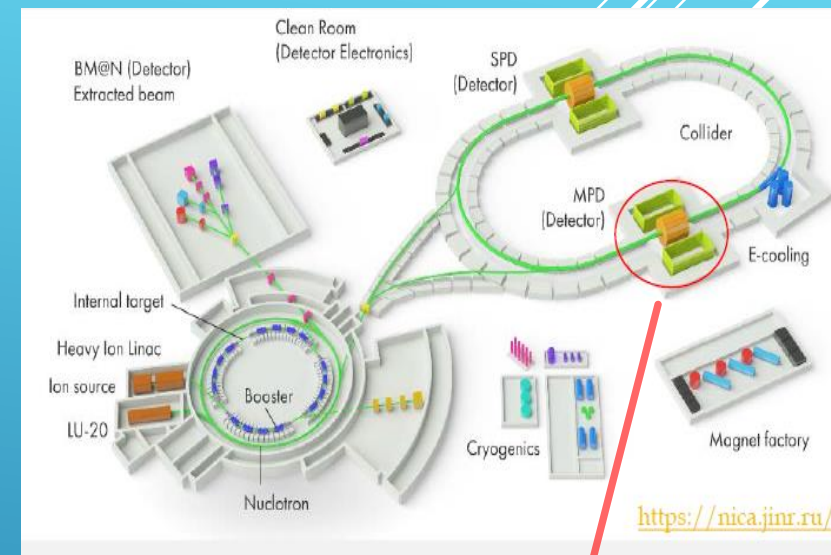
## Sub-systems:

- Electronics
- LV+HV system (CAEN)
- Gas and cooling systems
- Laser calibration system
- Slow control

## Integration TPC to MPD

- Electronics platform
- Cabling and piping
- Installation TPC to MPD

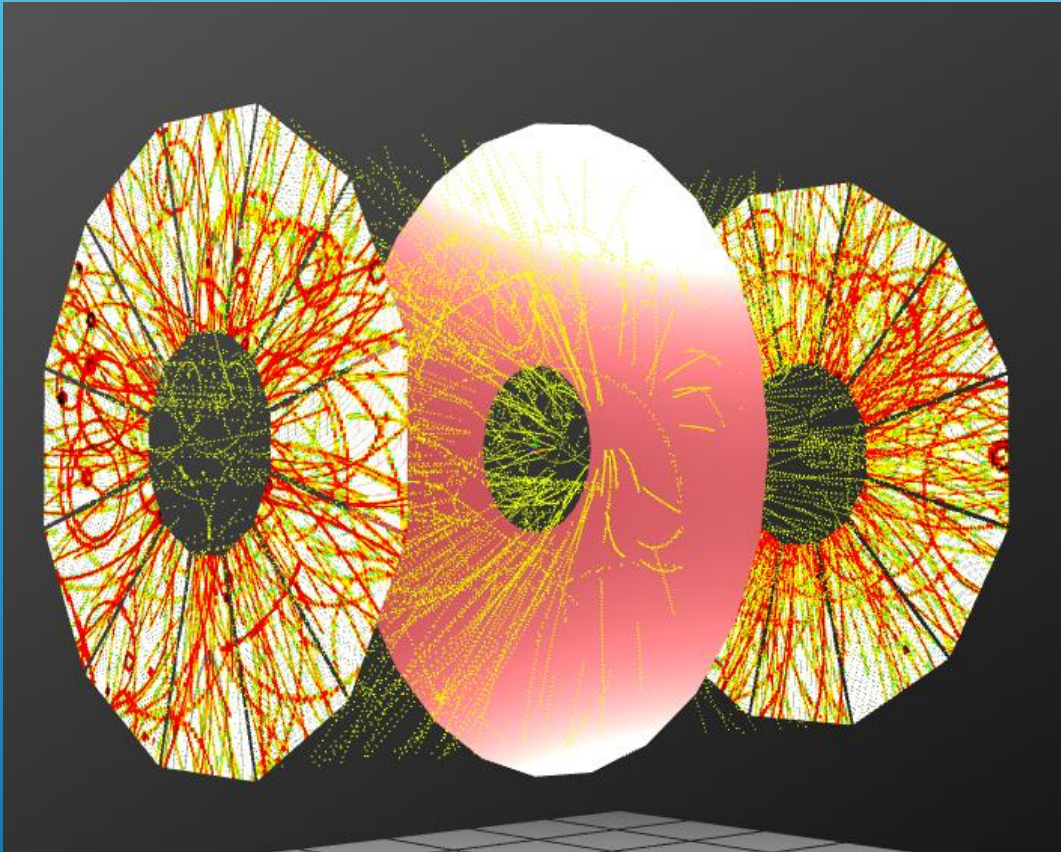
## Time schedule



Presented by S.Movchan

TPC team – 29 (JINR) + 20 (Belarus)

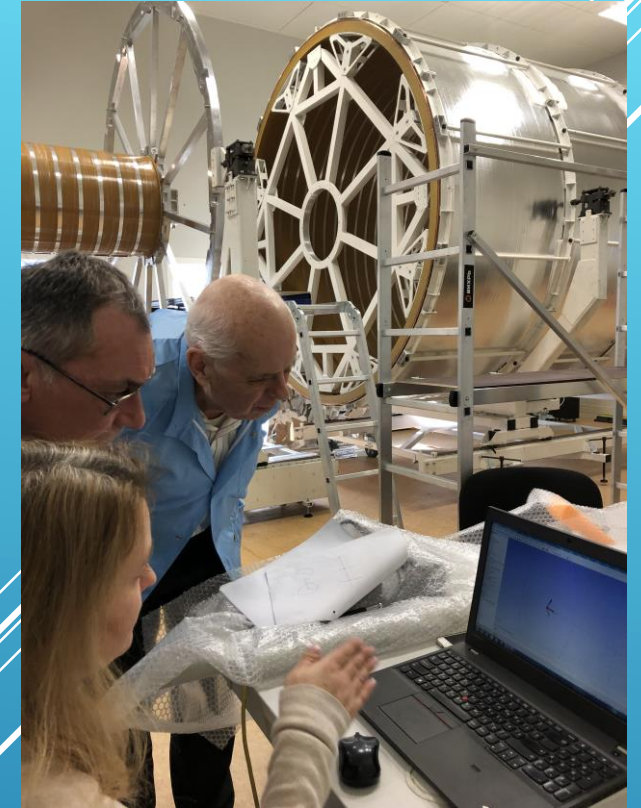
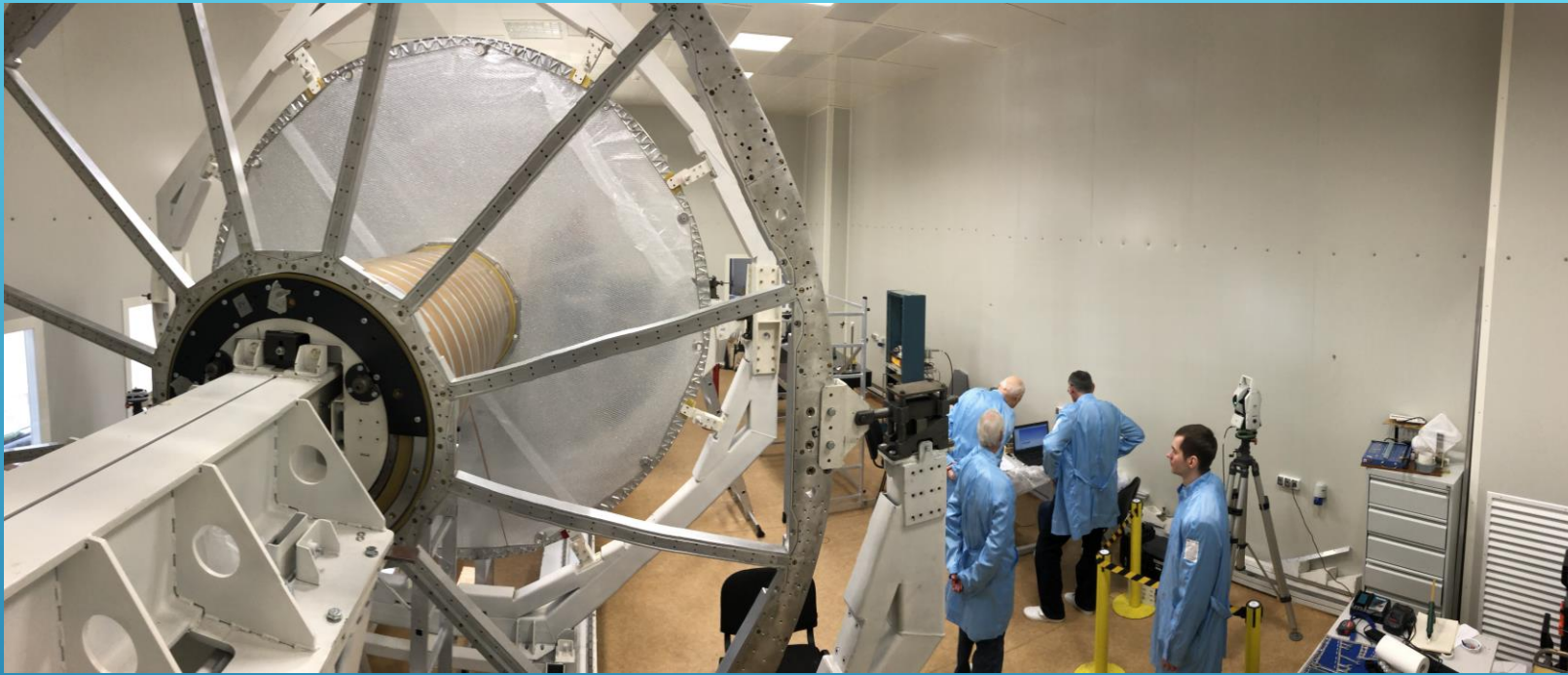
## MPD TPC MAIN PARAMETERS



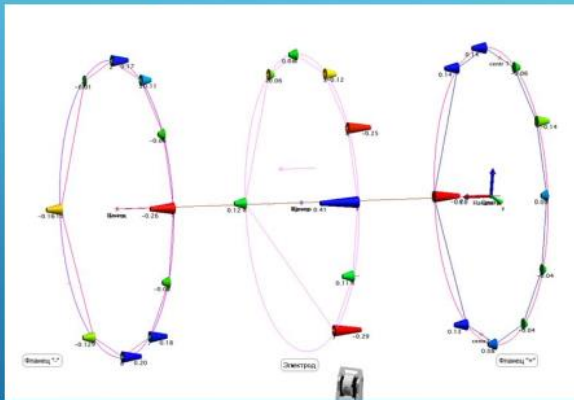
Item	Dimension
Length of the TPC	340cm
Outer radius of vessel	140cm
Inner radius of vessel	27 cm
Outer radius of the drift volume	133cm
Inner radius of the drift volume	34cm
Length of the drift volume	170cm (of each half)
HV electrode	Membrane at the center of the TPC
Electric field strength	~140V/cm;
Magnetic field strength	0.5 Tesla
Drift gas	90% Ar+10% Methane, Atmospheric pres. + 2 mbar
Gas amplification factor	~ 10 <sup>4</sup>
Drift velocity	5.45 cm/μs;
Drift time	< 30μs;
Temperature stability	< 0.5°C
Number of readout chambers	24 (12 per each end-plate)
Segmentation in φ	30°
Pad size	5x12mm <sup>2</sup> and 5x18mm <sup>2</sup>
Number of pads	95232
Pad raw numbers	53
Pad numbers after zero suppression	< 10%
Maximal event rate	< 7 kHz ( Lum. 10 <sup>27</sup> )
Electronics shaping time	~180 ns (FWHM)
Signal-to-noise ratio	30:1
Signal dynamical range	10 bits
Sampling rate	10 MHz
Sampling depth	310 time buckets



# TPC VESSEL ASSEMBLING



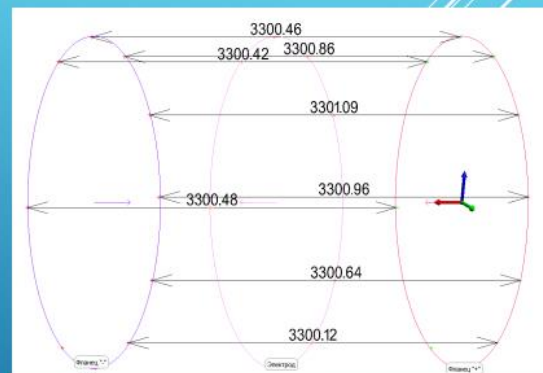
Flanges and HV electrode unflatness



Flanges unflatness – about 0.5 mm

HV electrode unflatness – about 0.7 mm

Flange to flange distance



$L = (3300.5 \pm 0.5)$  mm  
(nominal – 3300.0 mm)

**TPC body assembled with test rods for check TPC geometry by laser tracker AT-402 (reflector type -TBR (R=6.35 mm):**

- flanges unflatness – 0.5 mm
- asymmetry -  $L_{\text{left}} = L_{\text{right}} + 2$  mm



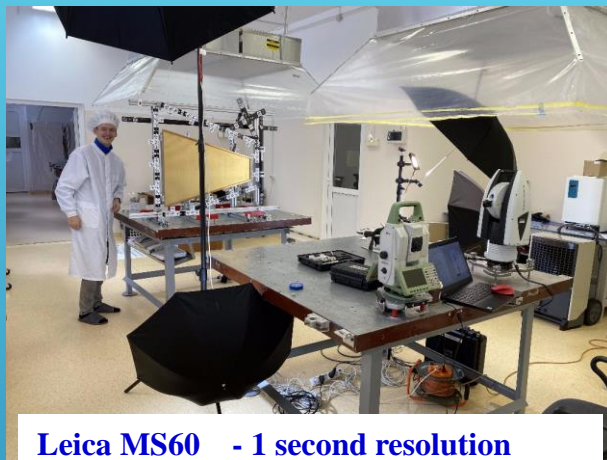
# ROC CHAMBERS AND GGS - GATING GRID SYSTEM : STATUS

Test set up for ROC certification



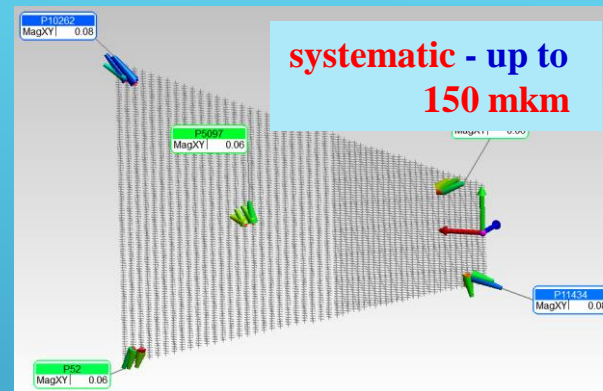
28 pc ROCs – tested

Test set up for pads calibration



Leica MS60 - 1 second resolution  
Leica AT960 +/-10 mkm +5 mkm/m  
Leica AT403 +/-15 mkm +6 mkm/m  
Scanner AS1+AT960 +/-50 mkm

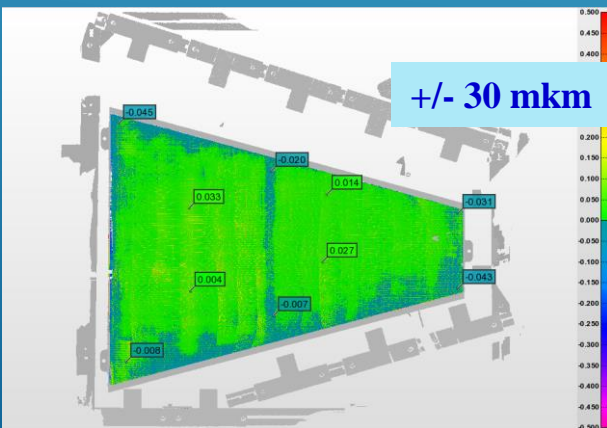
Check pads geometry



Full set of ROC alignment marks



Pad plane unflatness: example



24 pc serial ROCs + 4 spare – READY!

## Summary:

- measurements to do for all ROCs
- calibration of ROC marks and 3968 pads respect to ROC “reference hole” - in progress

ROC gating grid system: test set up



Pulse rise time ~ 900 ns, OK!



Mass-production – in progress  
Delivery to JINR – Dec 2024



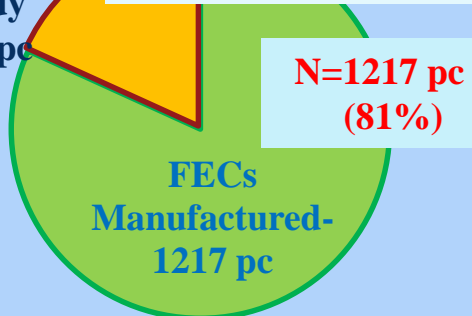
# TPC SUB-SYSTEMS: FE ELECTRONICS

**Production version of the FE card:**



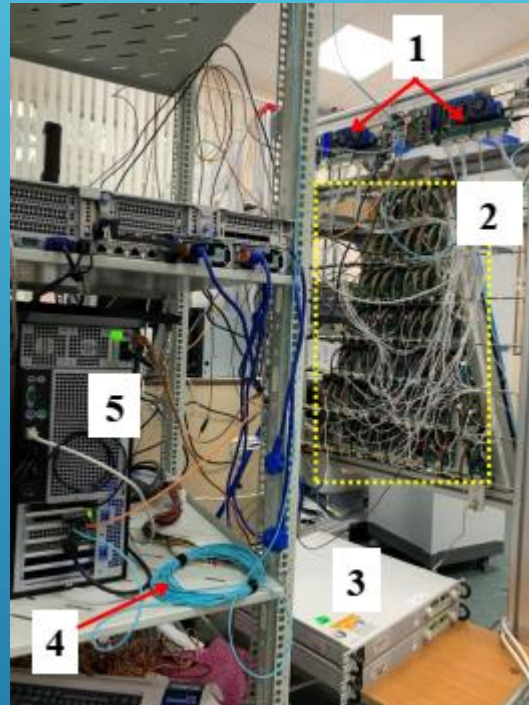
PCBs & components are ready for 271 pc

**TPC Front-End Cards Production status of April 1, 2024**



**19 ROCs chambers can be completed (from 24 ROCs)**

**DAQ prototype:**  
62 FE cards, RCU prototypes, ROC, 2pc LVDBs, server interface board - **tests ongoing**

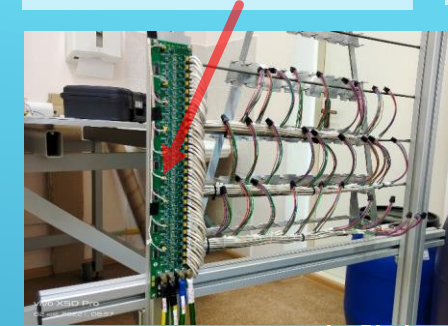


1. RCU prototypes
2. FECs on the ROC (62 pc)
3. LV power supply
4. DCU card connected with RCUs via fibers
5. Readout server

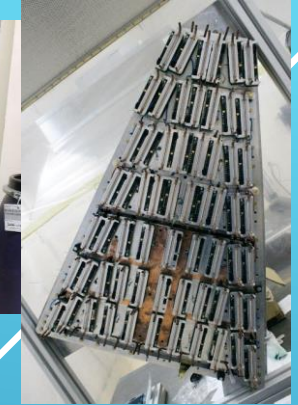
**RCU-64 controller:**  
testing with FEE



**LVN9 - LV stabilization module**



**FE radiators (water cooling)**



**60 pc LVN9 (INP BSU, Minsk):**

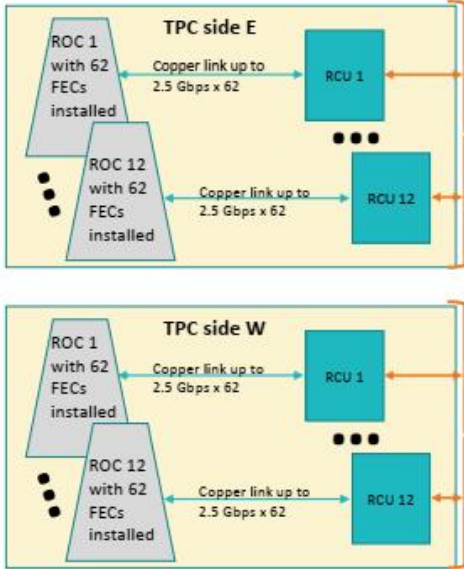
- modification LVN9 - **in progress**
- modification of LVN9 output voltage cables to FECs - **in progress**
- test of LVN9 with cooling radiator under full load (analog – 70 A, digital – 50 A) – **done**

- **1217 FECs** of 1500 were produced.
- Tests of the FEC basic functionality were shown the target characteristics (noise and stability).
- Testing of the readout system (on two **ROCs**) is **ongoing**
- RCU-64 controller **v1.1** – **ready for tests**



## TPC/MPD DAQ conceptual scheme

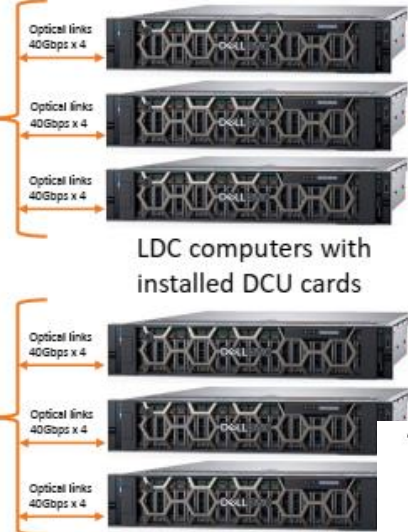
On the TPC (inside the MPD magnet)



Optical links  
40Gbps x 12

Optical links  
40Gbps x 12

Outside the MPD magnet



## TPC/MPD data acquisition system main parts

Front-End-Cards (FEC): 1488 pc., 95 232 10-bit ADCs in total

Readout and Control Units (RCU): 24 pc. in total

1488 ×



Data Concentrator Units (DCU): 6 pc. in total

6 ×



24 ×

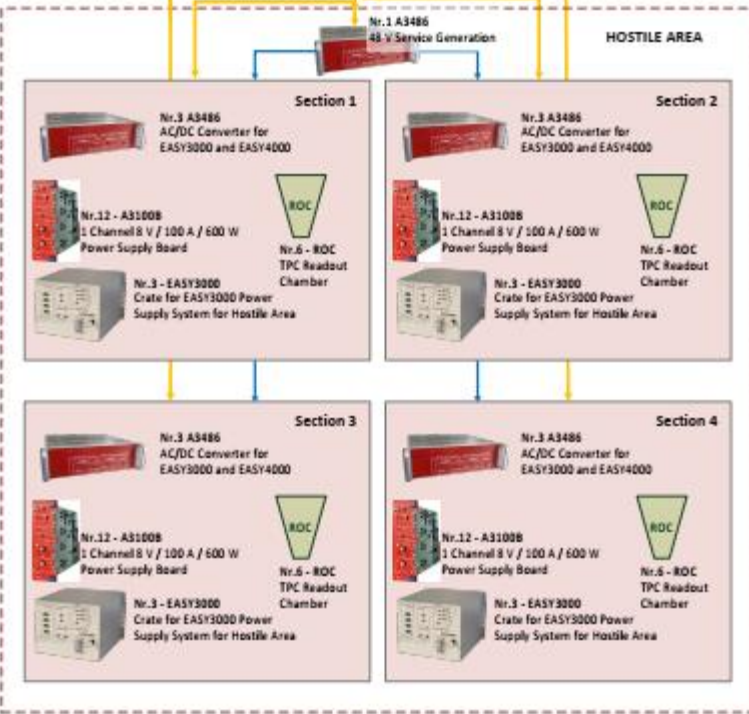
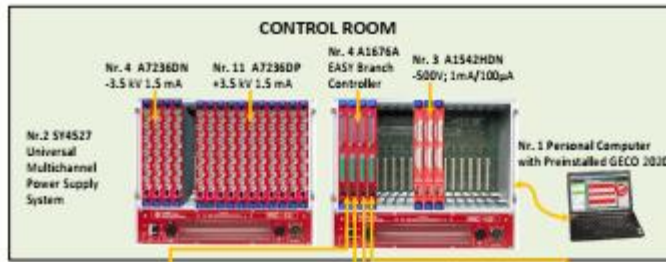


Local Data Concentrator (LDC) servers: 6 pc. in total

6 ×



# TPC SUB-SYSTEMS: LV+HV



LV&HV system based on CAEN rad. hard design:

(up to 2000 Gauss and 15 kRad)

- power converters A3486 AC/DC (380 V -> 48 V) – 15+3 pc
- EASY3000 crates – 14+2 pc
- LV module - A3100B (8V/100A) – 48+8 pc
- LV module - A3100HBP (14V/50A) – 6 +2 pc
- HV modules –A3540P (+4kV/1mA) – 8+3 pc
- HV modules –A3540N (- 4kV/1mA) – 2+2 pc

Status:

LV+HV system: JINR-CAEN contract signed

Expected delivery date to JINR: September 2023

test system – tests ongoing

LV cables (halogen free, low smoke):

S=25 mm<sup>2</sup> and 50 mm<sup>2</sup> – delivered

HV cables - delivered





# TPC SUB-SYSTEMS: GAS

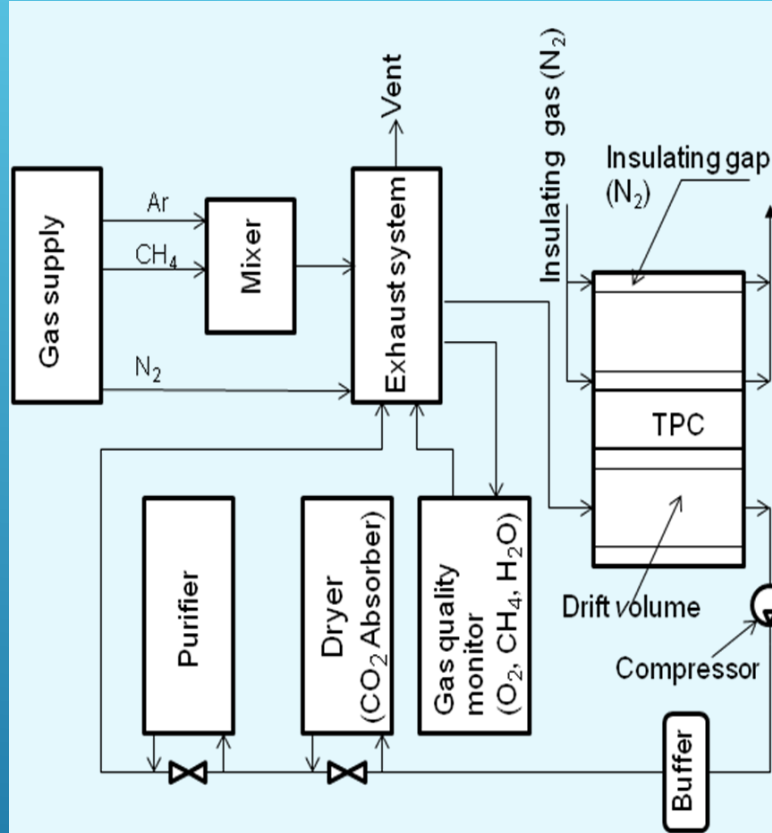
## Gas system main features:

- Drift gas mixture: 90%Ar + 10%CH<sub>4</sub> (P10);
- Insulating gas: N<sub>2</sub>;
- Operating pressure: atmospheric + 2.0 ± 0.03 mbar;
- Drift volume: 17640 liters;
- Insulating gaps volume: 2380 liters;
- Oxygen content: 5 ppm;
- Moisture content: 10 ppm;
- Recirculation rate of outer loop: 30 L/min;
- Recirculation rate of inner loop: 20 L/min

## Gases consumption:

Mode	Argon, m <sup>3</sup>	Methan, m <sup>3</sup>	Nitrogen, m <sup>3</sup>
TPC purging	84	5.4	36
Experiment:			
Per day	7.8	0.86	8.6
Per month	234	25.9	259

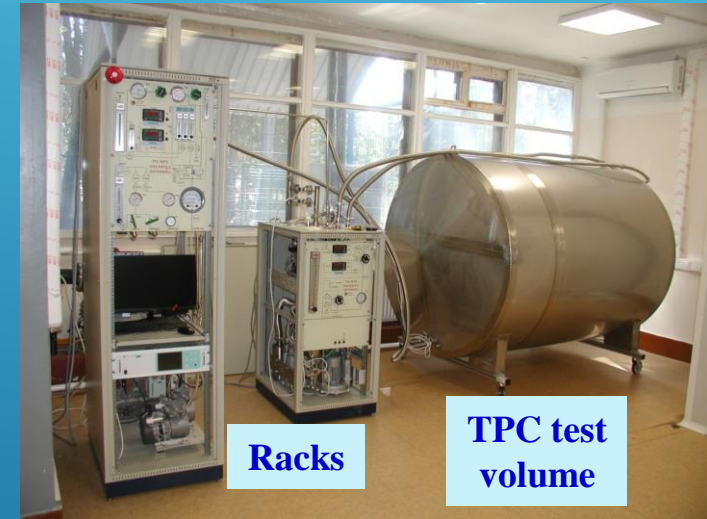
## Scheme



Gas system (Ar/CH<sub>4</sub>, 90:10)



Gas supply tanks



Racks

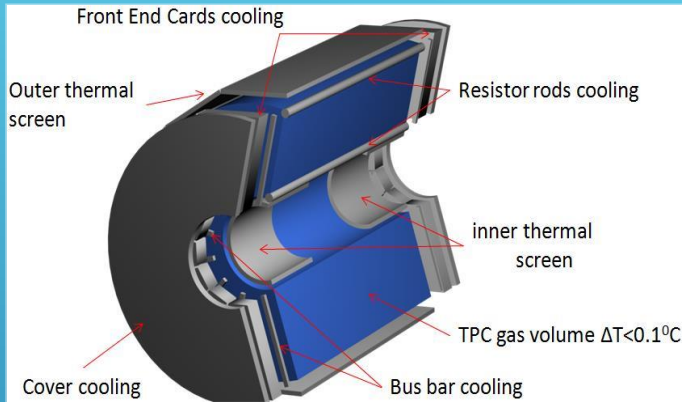
TPC test volume

Tests - in progress  
(H<sub>2</sub>O and O<sub>2</sub> sensors are replaced)  
**Ready for piping**

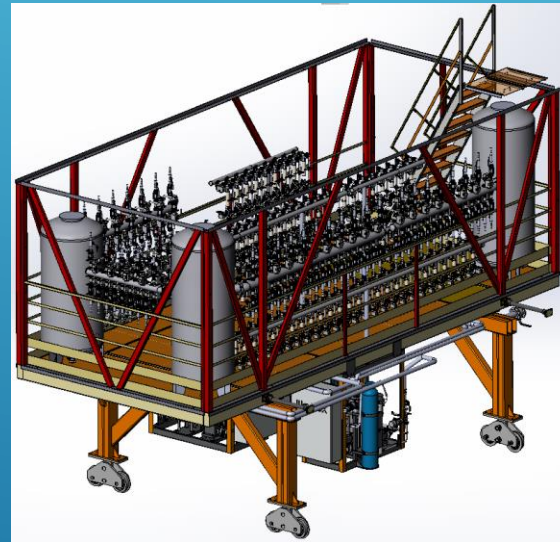


# TPC SUB-SYSTEMS: COOLING

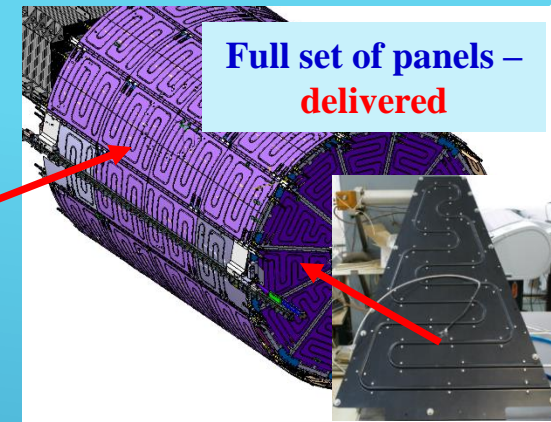
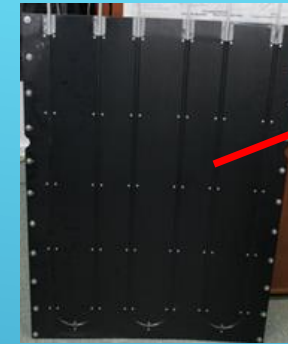
## Water cooling system – leak less option



## Cooling system - 1-st floor of the South platform



Design, optimization and procurements - **done**



Vacuum tanks



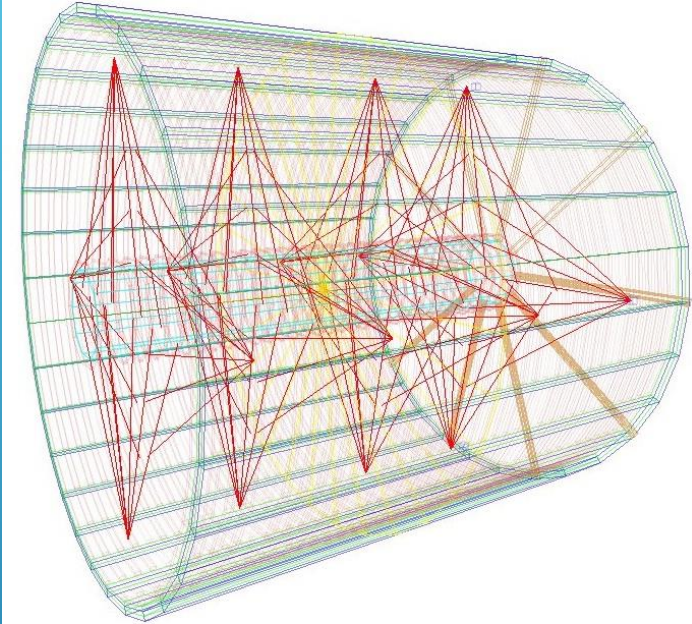
Heat exchanger

contract **JINR - INP BSU (Minsk):**  
components delivery – **September 30 2024**  
commissioning – **December 25 2024**

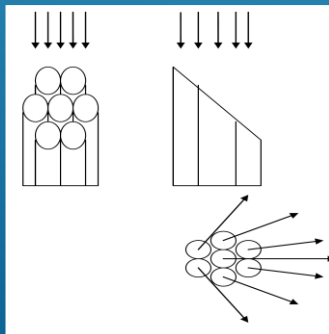
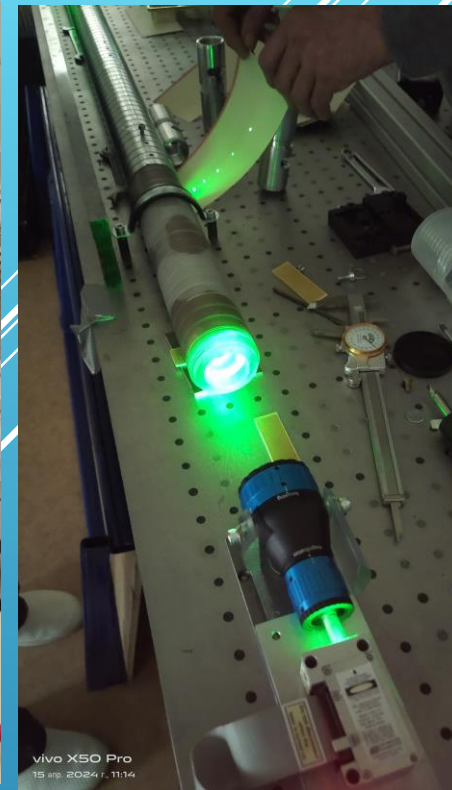
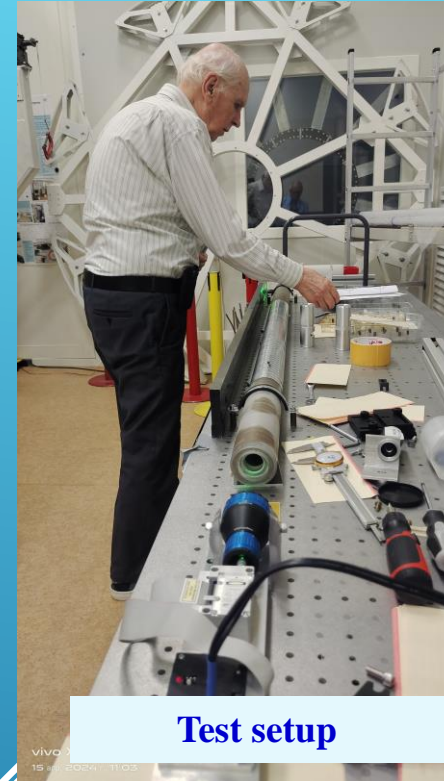
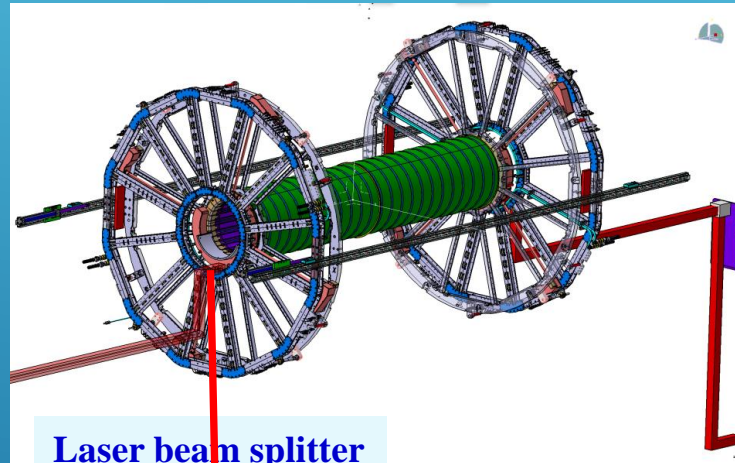
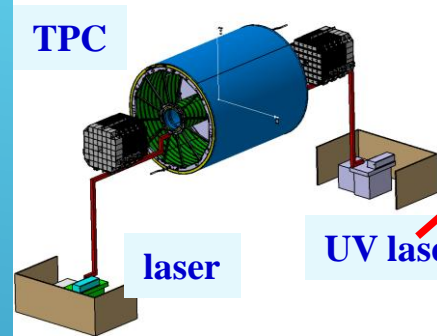


# TPC SUB-SYSTEMS: LASER CALIBRATION SYSTEM

Scheme for 1/2 TPC



- Laser "planes" - 4
- Micro-mirrors bundles per plane - 4
- Beams from micro-mirrors bundle - 7
- Laser "tracks" (N = 112x2) - 224



micro-mirror bundles

Laser beam monitor



in progress ...

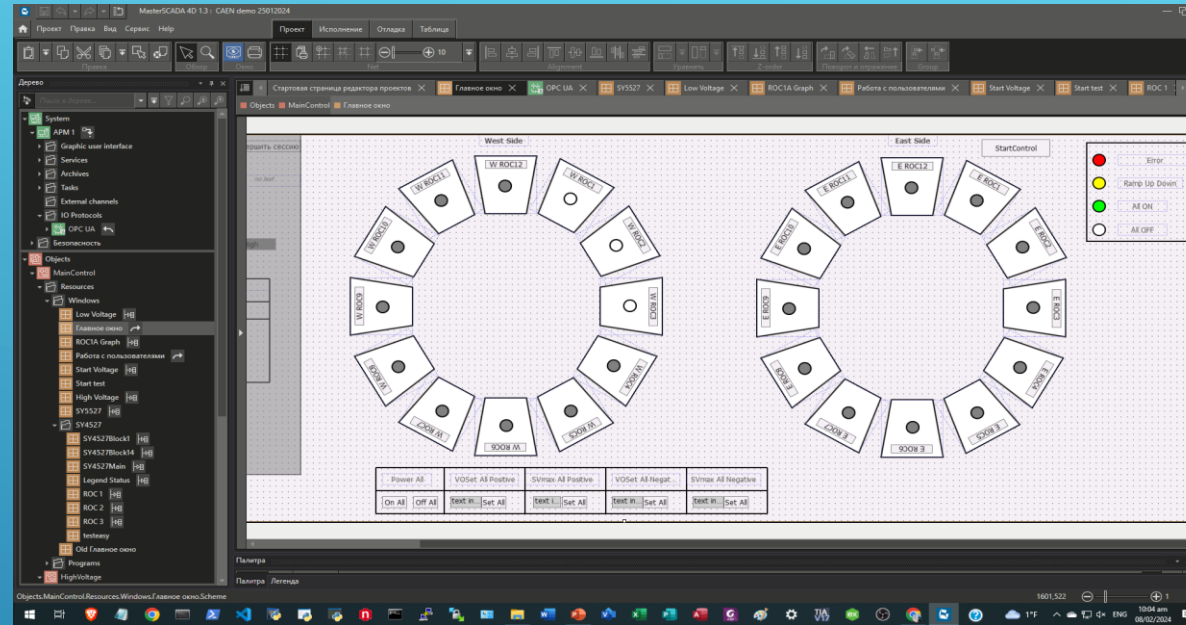


# TPC SUB-SYSTEMS: SLOW CONTROL

LV

CAEN LV test setup

Main window of LV+HV GUI based on MasterScada 4D

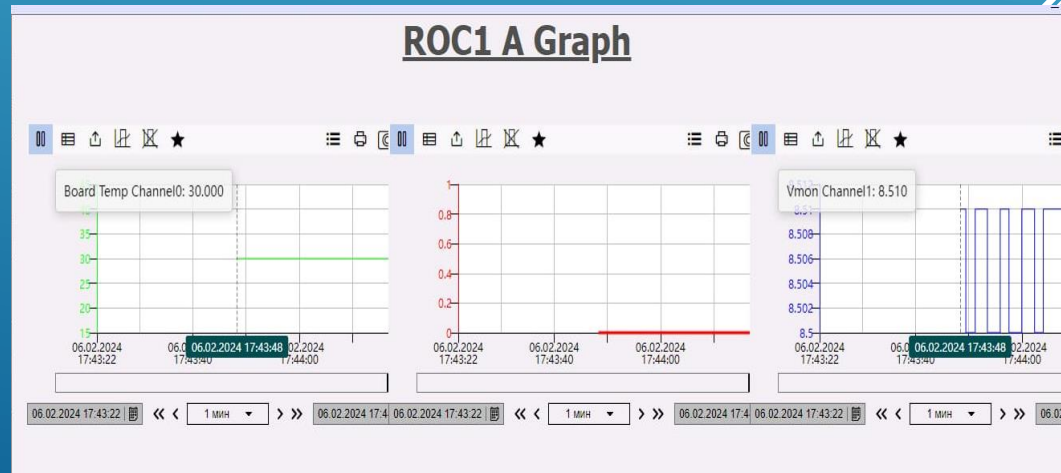


Low Voltage									
Name	PowerON/OFF	IOSet	Imon	V0Set	Vmon	Status	Trip	SerNum	RemBdName
CH000	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
CH001	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
CH002	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
CH003	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
CH004	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
CH005	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
CH006	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
CH007	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
CH008	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
CH009	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
CH010	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

HV

W ROC 1									
Name	Power	V0Set	IOSet	Vmon	Imon	Status	Trip	SVmax	
A1 CH000 Block1 (PID 27072)	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
A2 CH001 Block1 (PID 27072)	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
A3 CH002 Block1 (PID 27072)	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
A4 CH003 Block1 (PID 27072)	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	1420	<input type="checkbox"/>
CE CH000 Block14 (PID 20698)	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

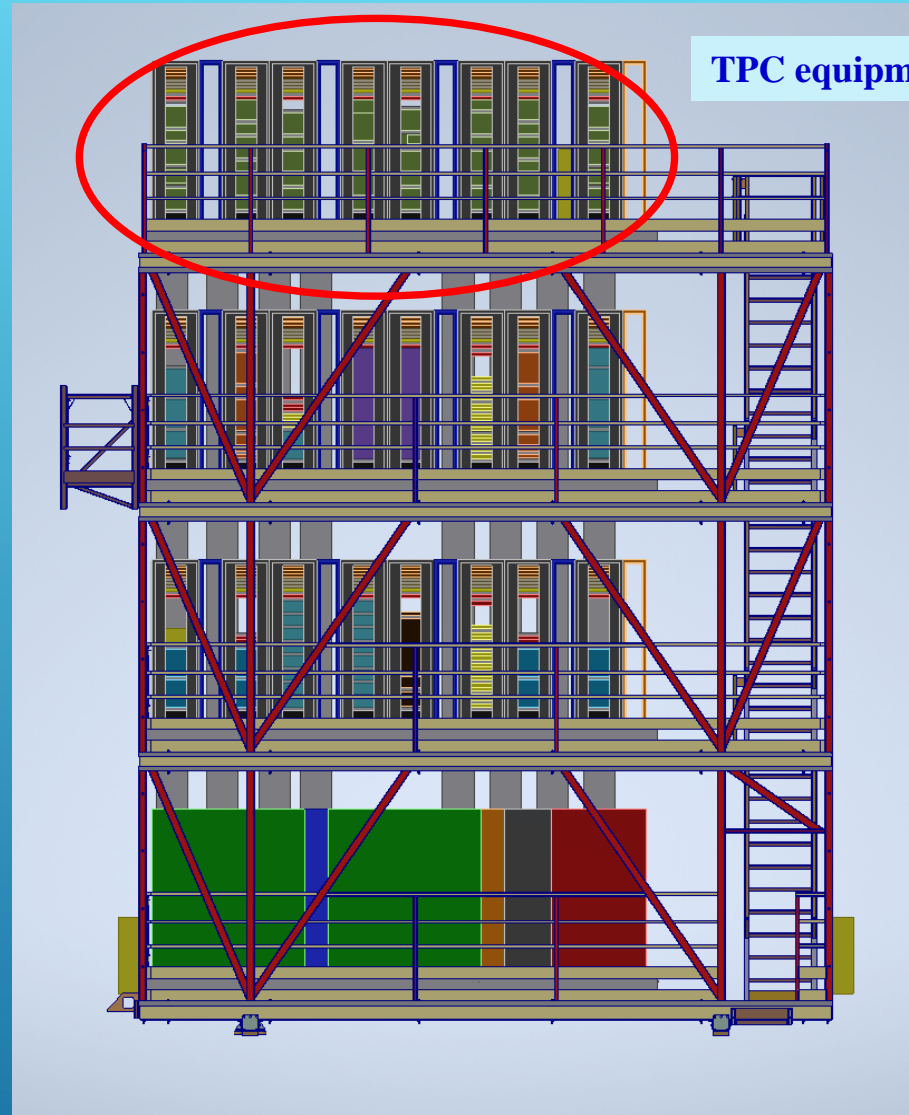
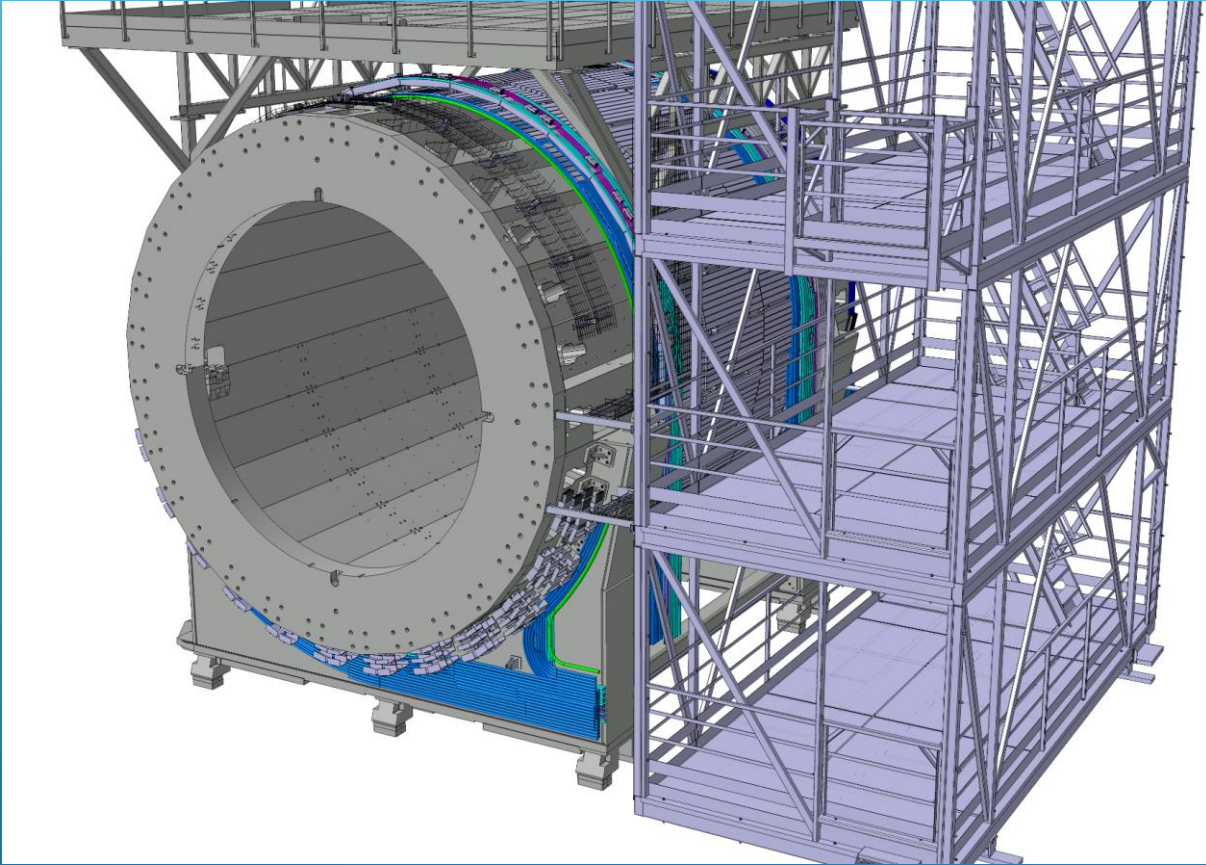
DATA transfer from MasterScada 4D to the DB POSTGRESQL16 – OK!



in progress ...

# INTEGRATION: TPC RACKS

Common view of North platform

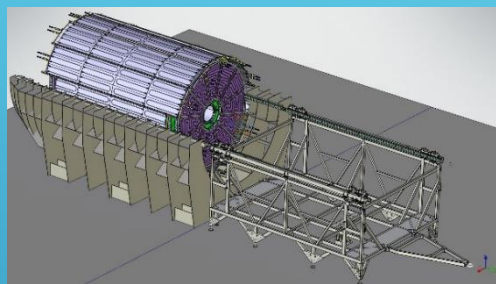


Integration – in progress ...

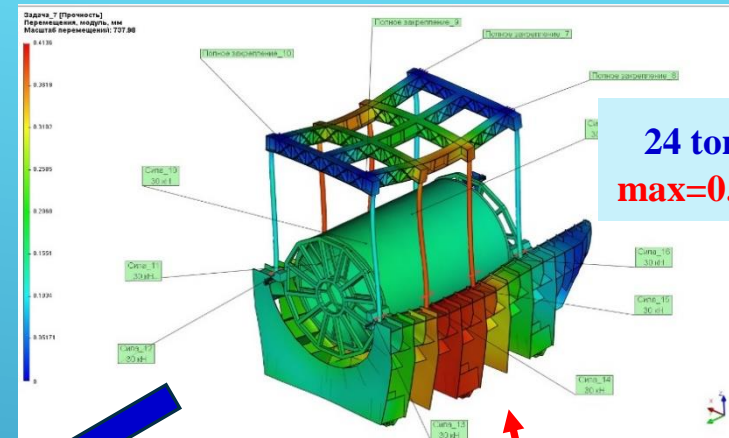


# TOOLING FOR INSTALLATION TPC TO MPD

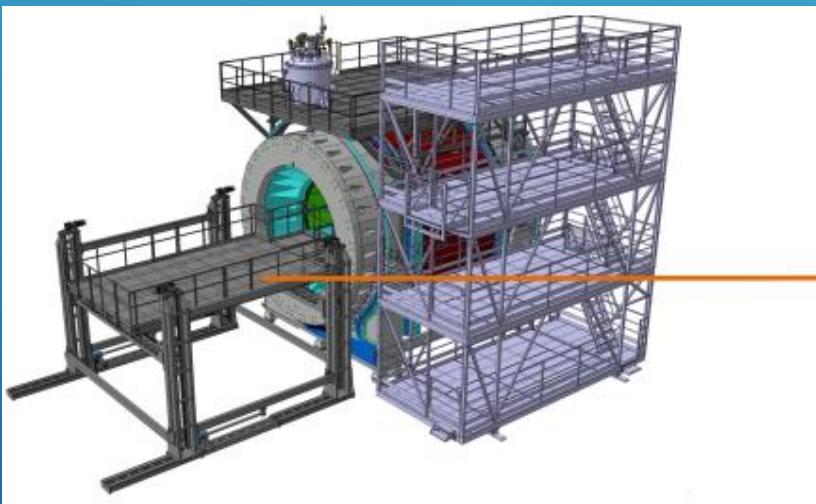
Bld. 217



Bld. 17 (MPD)



24 tons,  
max=0.41 mm



Lifting platform

Tooling for installation TPC to MPD delivery - August 2024  
TPC installation to MPD - April 12 – June 10 2025



Tooling for installation TPC to MPD – manufactured  
Delivery to JINR – December 30 2024

## STATUS AND TIME SCHEDULE

### Status:

TPC vessel	in progress
ROCs (24+6 spare)	ready
FE electronics	81% manufactured (1217 FECs from 1500)
Gating grid system	ready
HV+LV systems	ready for start installation
Gas system	ready for start piping
Cooling system	in progress
Laser system	in progress
Slow control system	in progress

### TPC assembling:

#### TPC:

TPC vessel assembled	Dec 30 2024
ROC chambers installation	Jan 2025
TPC tests (with laser tracks and cosmic ray)	Feb - May 2025
TPC rails and installation tooling	
Rails installation to ECAL support structure	July 2 2024
Tooling for installation TPC to MPD delivery	October 30 2024
TPC+ECAL cooling systems (INP BSU, Minsk):	
Delivery to JINR	Sept 30 2024
Systems assembling and piping	Oct-Nov 2024
Commissioning	Dec 25 2024
TPC installation to MPD	April 12 - June 10 2025
Cabling	Jan-June 2025
MPD commissioning	June - July 2025
Strat of technical RUN with beams	July 27 2025

**Thank you !**





# MPD TPC UPGRADE



## TPC base line option:

- radiation length
- results of radiation length optimization

## Spark protection:

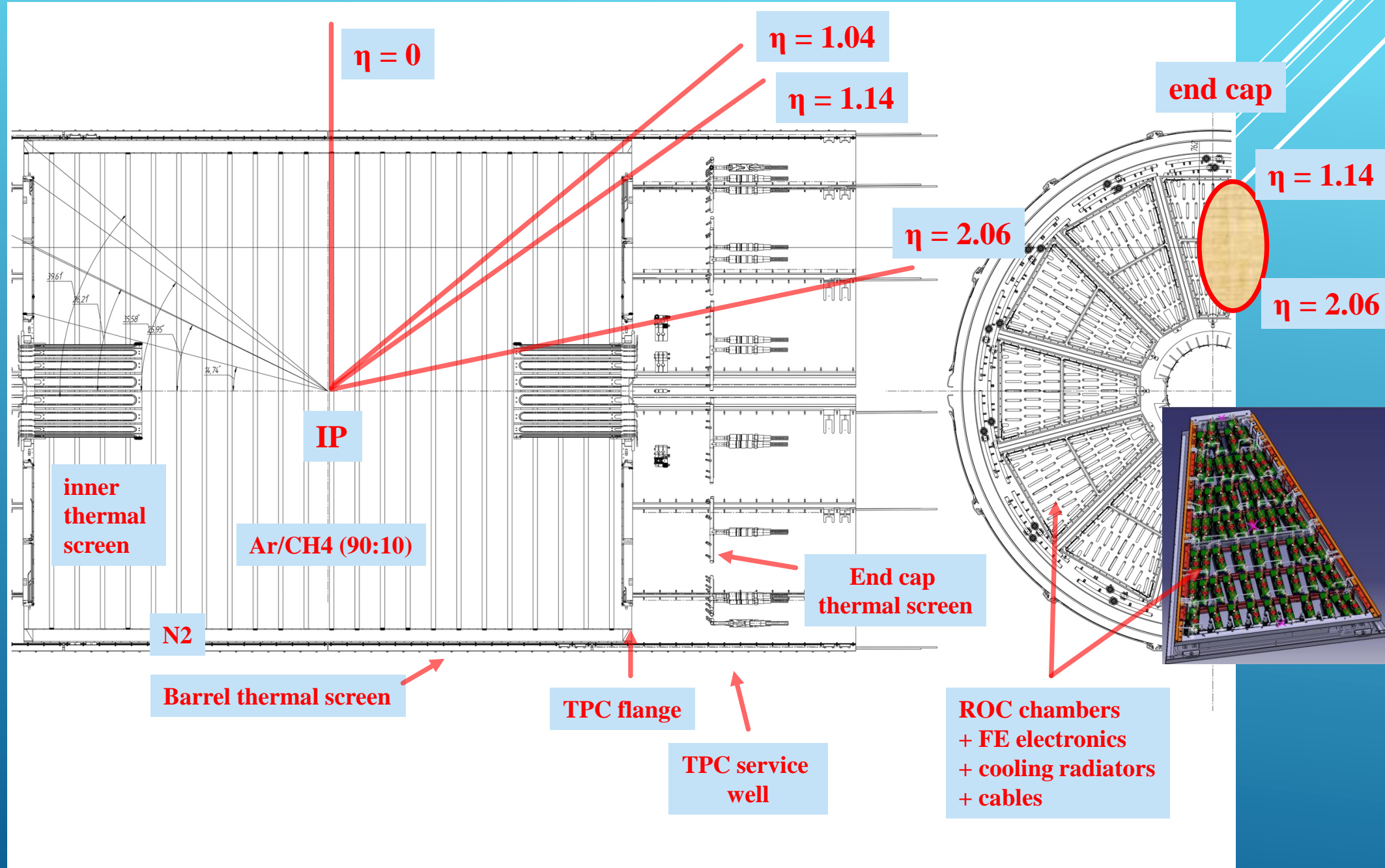
- diamond like carbon (DLC) coating of a anode

## Upgrade options:

- WEM+ DLC prototype
  - MictoMegas + DLC prototype
- or typical solutions**
- Standard GEMs (like ALICE)
  - Micromegas + GEM (CERN)

Presented by S.Movchan

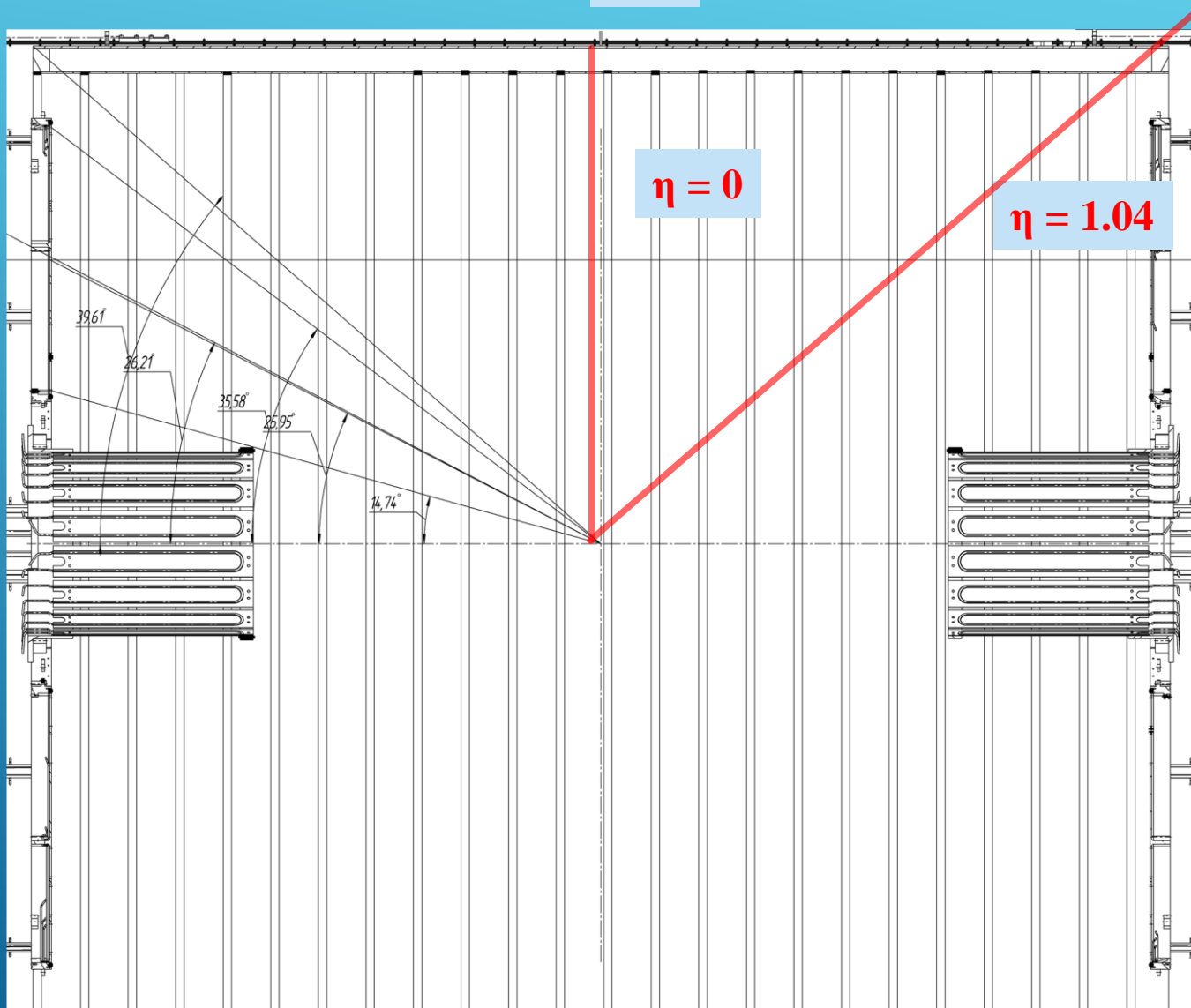
# MPD TPC RADIATION LENGTH





# MPD TPC RADIATION LENGTH: BARREL $\eta = (0 \div 1)$

TPC



	Base line option	
	for $\eta = 0$ $\Theta = 90^\circ$	for $\eta = 1.04$ $\Theta = 38.87^\circ$
C1 h=3 mm + Al foils	1.061	1.689
N <sub>2</sub> (gap C1-C2) h=65 mm	0.020	0.032
C2 h=3 mm + Al strips on C2	0.958	1.525
TPC gas mixture (L=989 mm)	0.771	1.228 (L=1574.8 mm)
Potential degrader rods + field cage	0.085	0.135
C3 h=4.05 mm + Al strips	1.275	2.030
N <sub>2</sub> (gap C3-C4) h≈67 mm	0.020	0.032
C4 h=6.4 mm	1.972	3.140
TPC shielding Al, h=0.1 mm	0.112	0.178
TPC thermal-screen (top) Al + H <sub>2</sub> O, h=1.5mm	2.943	4.686
TPC thermal-screen (bottom) Al + H <sub>2</sub> O, h=1.5mm	-	-
Air (C4 up to TOF) h = 60 mm	0.020	0.032
<b>Sum:</b>	<b>≈ 9.24</b>	<b>≈ 14.71</b>

for barrel (up to  $\eta=1$ ):  
 $X/X_0 = (9.24 \div 14.71) \%$

# MPD TPC RADIATION LENGTH: UPGRADE

TPC radiation length for flange (horizontal)					
MWPC	for perpendicular to chamber	for $\Theta \approx 25.03^\circ$ $\eta = 1.51$	GEM+optimization	for perpendicular to chamber	for $\Theta \approx 25.03^\circ$ $\eta = 1.51$
C1+C2 +N2 +Ar/CH4			C1+C2 +N2 +Ar/CH4		
Sum [C1+N2(gap C1-C2) + C2 + gas mixture (L=1164.8mm)]:	-	5.65	Sum [C1+N2(gap C1-C2) + C2 + gas mixture (L=1164.8 mm)]:	-	5.65
ROC	-		ROC	-	
1. Wires	0.30	0.33	1. 4 GEM foils (Cu - 8x5 $\mu$ m =40 $\mu$ m, kapton - 4x50 $\mu$ m =200 $\mu$ m)	0.35	0.385
2. Pad plane h=3.4mm + inside glue	2.83	3.12	2. Pad plane h=3.4 mm (new) + inside glue	~2.24	~2.47
3. Insulating plate h=3 mm	1.88	2.08	3. Insulating plate h=1.5 mm	0.94	1.04
4. Al frame h=5 mm & ROC reinforce rib + ROC cooling tube (Cu) with water	6.54 + 0.91	7.22 + 1.00	4. Carbon frame h=2.5 mm & ROC reinforce rib + ROC cooling tube (Al) with water	1.89 + 0.59	2.09 + 0.65
5. Epoxy glue (2x0.1 mm)	0.056	0.062	5. Epoxy glue (2x0.1 mm)	0.056	0.062
6. Connectors + solder	0.34	0.38	6. Connectors+ solder	0.34	0.38
Air gap L=100 mm	0.033	0.036	Air gap L=100 mm	0.033	0.036
ROC MWPC sum:	12.89	14.23	ROC GEM sum:	~6.44	~7.11
FE (based on SAMPA chip)			FE (based on SAMPA chip)		
Components	0.33	0.36	Components (new)	0.165	0.18
FE PCB – (2x12 layers)x2	2.32	2.56	FE PCB – 2x12 layers → FE Controller card will be removed to sides of ROC	1.16	1.28
Connectors + Solder	0.34	0.38	Connectors + Solder	0.34	0.38
FE sum:	2.99	3.30	FE sum:	1.67	1.84
FE Cooling			FE Cooling		
Al radiators + Cu & Al pipes + water	7.10 + 3.68	7.84 + 4.06	Al radiators + Al pipes + water	3.81+ 2.07	4.21+ 2.28
FE Cooling sum	10.78	11.90	FE Cooling sum:	5.88	6.49
LV & DAQ+SC cables			LV & DAQ+SC cables		
LV + DAQ+SC cables + flat cables (Cu)	~ 8.82 + 0.19	~ 8.82 + 0.21	LV & DAQ+SC cables (Al) + flat cables (Cu)	~ 2.36 + 0.19	~ 2.36 + 0.21
TPC thermal screen			TPC thermal-screen		
TPC thermal-screen Al (flange) +Al (clamps) [m(Al) = 21 kG]	~1.46	~1.61	TPC thermal-screen Al (flange) + Al (clamps) [m(Al) = 21 kG]	~1.46	~1.61
+ H <sub>2</sub> O	~0.01	~0.01	+ H <sub>2</sub> O	~0.01	~0.01
Summary:	~37.14	~45.73		~18.01	~25.28

for end caps  $\eta = (1.14 \div 2.06) X/X_0$ :

**46 % -> 25%**



## MPD TPC RADIATION LENGTH: OPTIMIZATION (UPGRADE)

**Goal** - decrease  $X/X_0$  from 40% up to (20÷25)% for TPC End Caps:

- MWPC - > MPGD (GEMs, MicroMegas, ThGEM ...)
- ROC chamber Al frame -> to composite frame
- FE electronics: -> integrate SAMPA chips with ROC chamber pad plane  
-> move boards with FPGAs from chamber to flange arms
- LV Cu cables - > Al cables

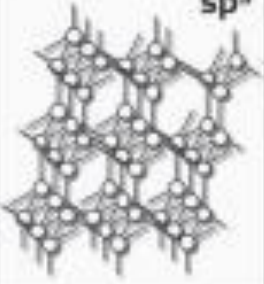


## MPGD DISCHARGE ROBUSTNESS: **DLC** COATING

**MPGD discharge robustness:**

**- diamond like carbon (**DLC**) coating of a electrodes**

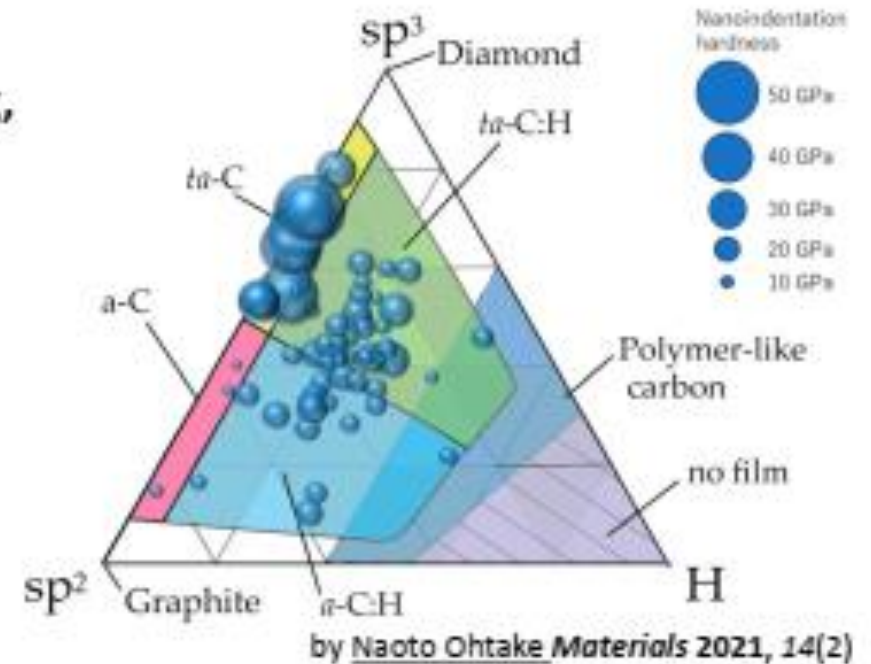


## DLC – Diamond-Like Carbon

Diamond	D L C (Diamond-like carbon)	Graphite
$sp^3$	$sp^3 + sp^2$	$sp^2$
		

uploaded from pcs-instruments.com

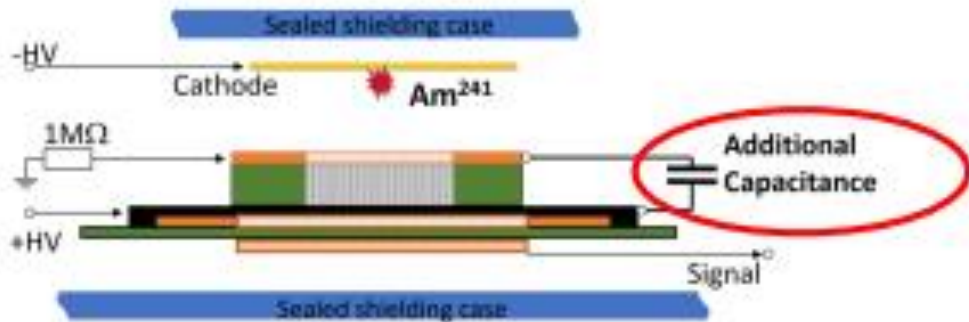
Widely used as a hardening coating, anti-reflective optical coating, decorative



In High Energy Physics is used as a resistive coating for MPGDs

# EXAMPLE: R-WEM PROTOTYPE WITH DLC ANODE

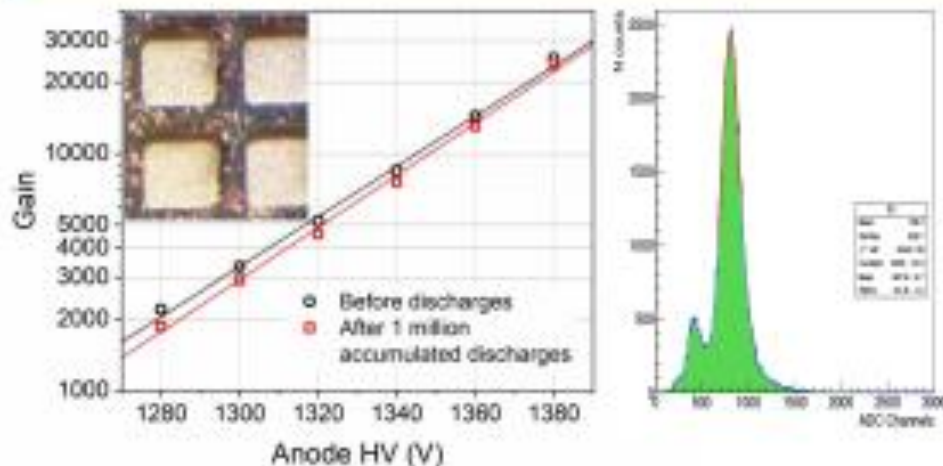
## Effect of Multiple Discharges on Accumulated Damage in R-WEM with DLC Anode



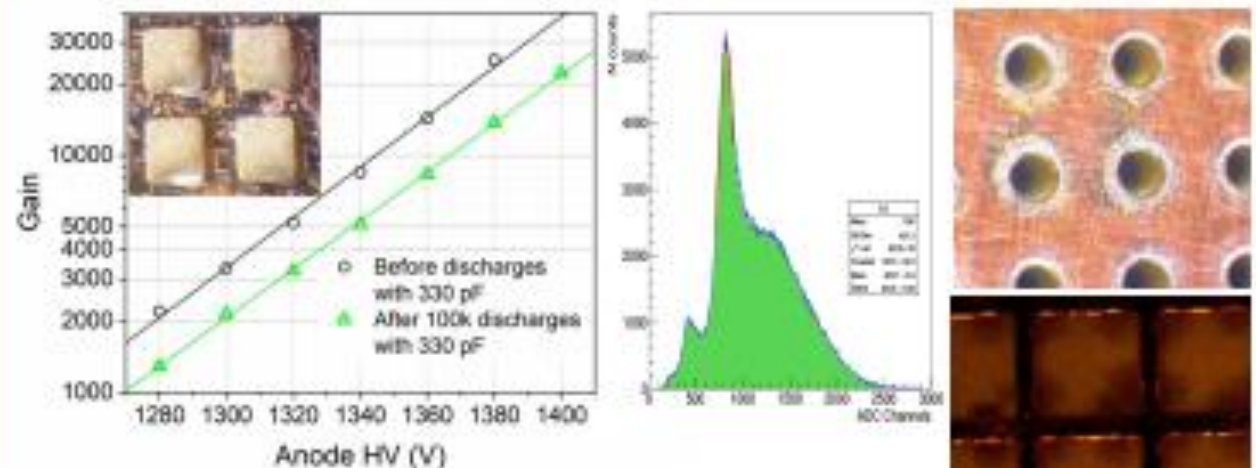
The discharge events initiated by an  $\text{Am}^{241}$  alpha source.  
The circular alpha source 3 mm in diameter, activity of 33 Bq

Active Area	Capacitance with the frame	Energy of discharges	Number of discharges
10 x 10 mm <sup>2</sup>	34 pF	29 μJ	1,000,000
60 x 60 mm <sup>2</sup>	360 pF	0.3 mJ	100,000
100 x 100 mm <sup>2</sup>	1 nF	0.9 mJ	100,000

To simulate a large area R-WEM we used an Additional Capacitance, in parallel with R-WEM anode and top electrode



No damage is observed after **1,000,000 discharges** for active area **10 x 10 mm<sup>2</sup>**

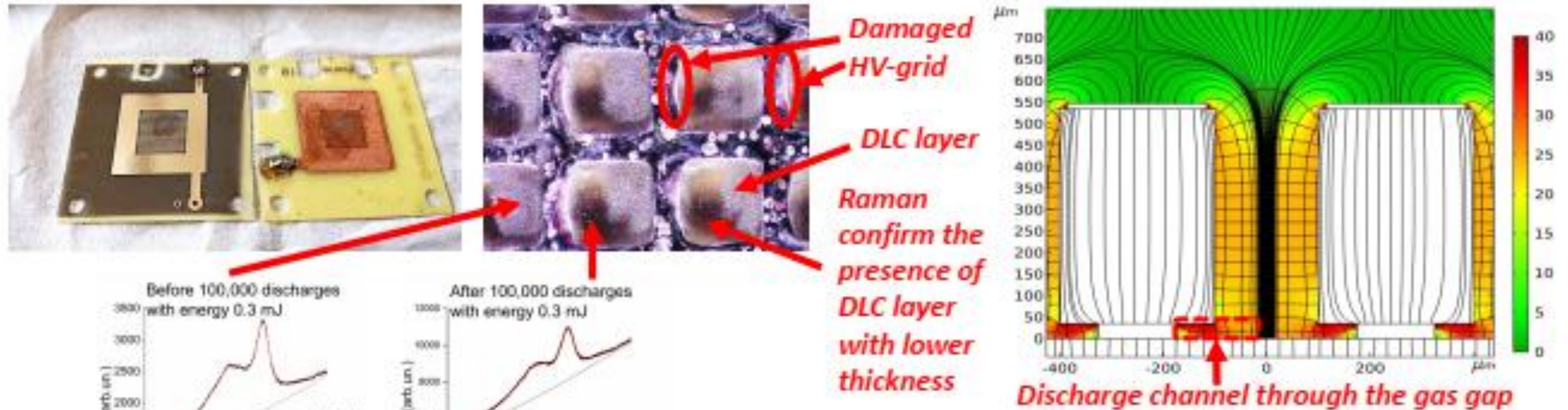


After **100,000 discharges** for active area **60 x 60 mm<sup>2</sup>** a slight visible damage was observed



## EXAMPLE: R-WEM PROTOTYPE WITH DLC ANODE

### Effect of Multiple Discharges on Accumulated Damage in R-WEM with DLC Anode



The further increase of the discharge energy by adding a capacitance up to  $C = 1$  nF (active area  $100 \times 100$  mm<sup>2</sup>) resulted in a significant damage to the DLC layer and the perforated FR4 board after 100,000 discharges. Both plates of the detector were significantly damaged

The damage of DLC layer itself is small, because the discharge current pass through the gas gap

- The HV-grid has a thickness of 35  $\mu\text{m}$  and this results in a gap between the Perforated FR4 board and the Anode board.
- The electric field strength in this gap has a local maximum relative to the center of the multiplication hole.
- When the discharge occurs, the discharge channel does not terminate on the resistive layer directly under the multiplication hole but instead goes above the resistive layer through the gas in the gap and terminates into the metal of the charge evacuation grid.
- In this case the resistive DLC layer is completely bypassed and do not provide the expected detector protection.

7<sup>TH</sup> INTERNATIONAL CONFERENCE ON MICRO PATTERN GASEOUS DETECTORS  
REHOVOT, ISRAEL  
11–16 DECEMBER 2022

## Effect of multiple discharges on accumulated damage to the DLC anode layer of a resistive Well Electron Multiplier

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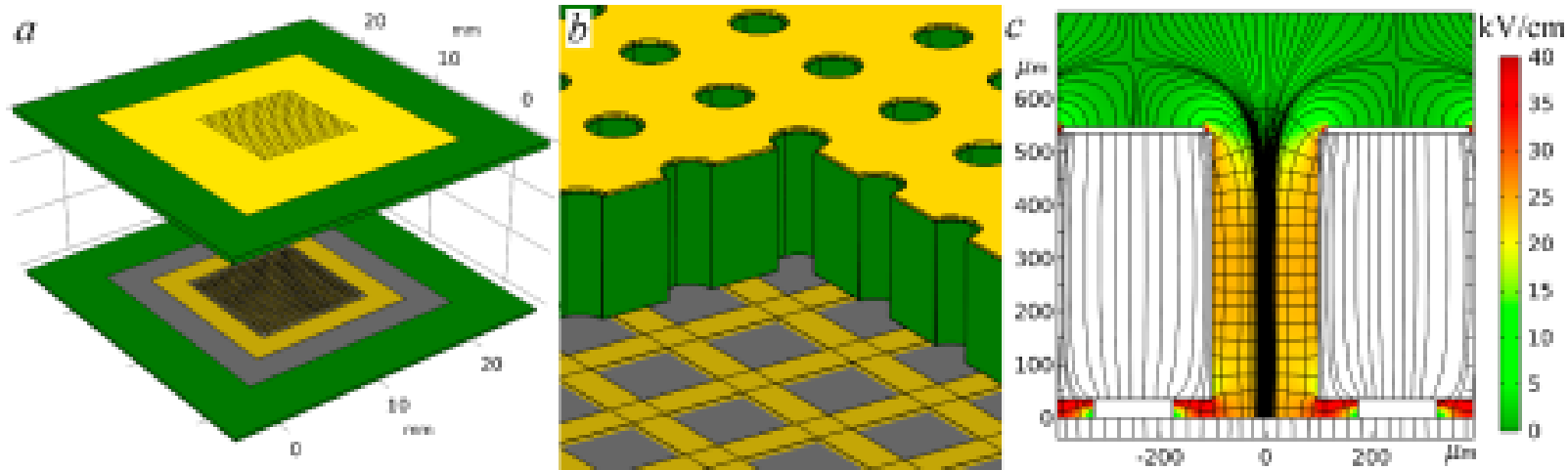
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# WEM+DLC PROTOTYPE

## Prototype sketch



**Figure 1.** The sketch of WEM detector as a composition of two boards (a), Close-up sketch showing the position of the perforated FR4 board relative to the anode (b), electric field distribution modeled by Comsol Multiphysics software for +1300 V anode voltage (c).

## Well Electron Multiplier (WEM)

(hole pitch=400 μm, D=200 μm  
thickness h=400 μm, active size =  
10x10 mm, Cd=34 pF)

DLC R= 30 MΩ/sq

Ar/CO<sub>2</sub> (90:10)

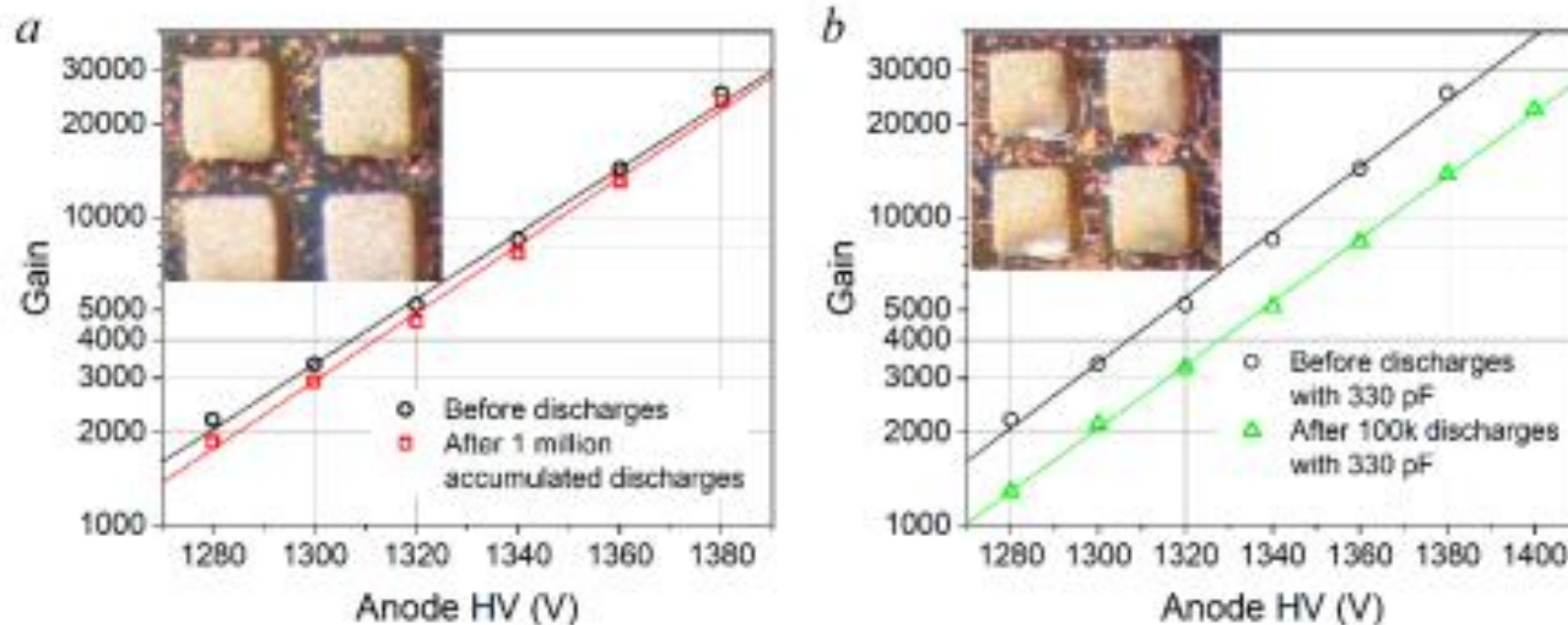
Edrift=1 kV/cm

U<sub>a</sub>=+1310 V (gas gain G=3500)

Fe-55 - for gas gain control

Am-241, 33Bq – alpha particles (induce discharges with rate about N=30 cps)

## WEM+DLC PROTOTYPE



**Figure 2.** Gain vs HV before and after accumulating  $10^6$  (a) and  $10^5$  (b) discharges with an energy of  $29 \mu\text{J}$  and  $0.3 \text{ mJ}$ , respectively. The insets to the figures show the photographs of the anode plate with DLC layer after discharges of the corresponding energy.

For energy discharge:

$29 \text{ mJ}$  ( $C_d=34 \text{ pF}$ ) : 1 million discharges – **NO effect**

$300 \text{ mJ}$  ( $C_d=330 \text{ pF}$ ) : 100 k discharges – gas gain drop, but **NO DLC degradation yet**

$900 \text{ mJ}$  ( $C_d=1\text{nF}$ ): 100 k discharges – **visible DLC damage**

**=> max segment size is  $60 \times 60 \text{ mm}$**





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### Improving the robustness of Micromegas detector with resistive DLC anode for the upgrade of the TPC readout chambers of the MPD experiment at the NICA collider



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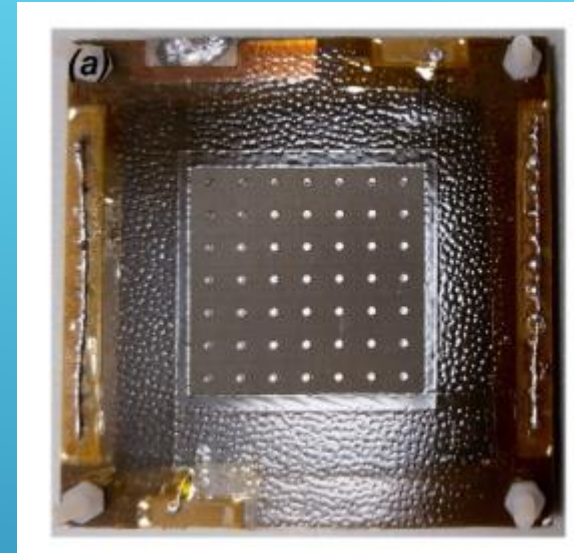
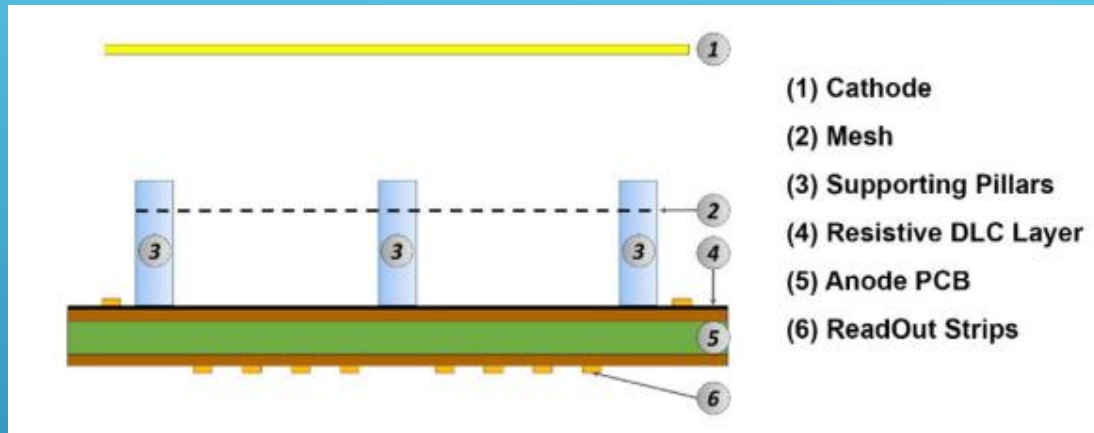
<sup>e</sup> Physical-Technical Institute of National Academy of Sciences of Belarus, Minsk, Belarus

<sup>f</sup> Faculty of Physics, Belarusian State University, Minsk, Belarus

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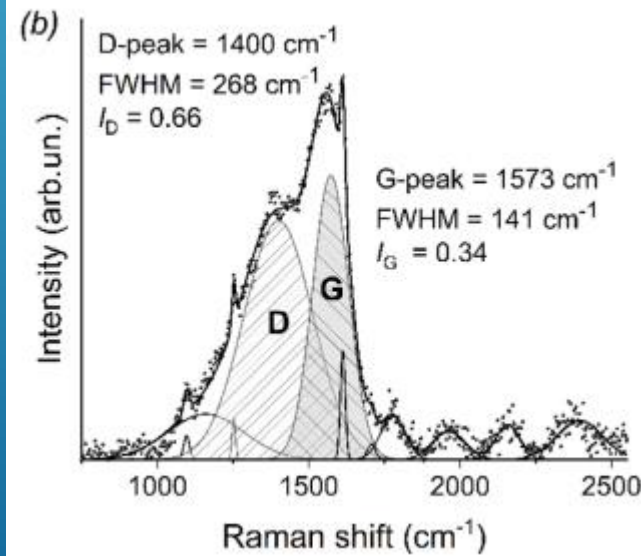
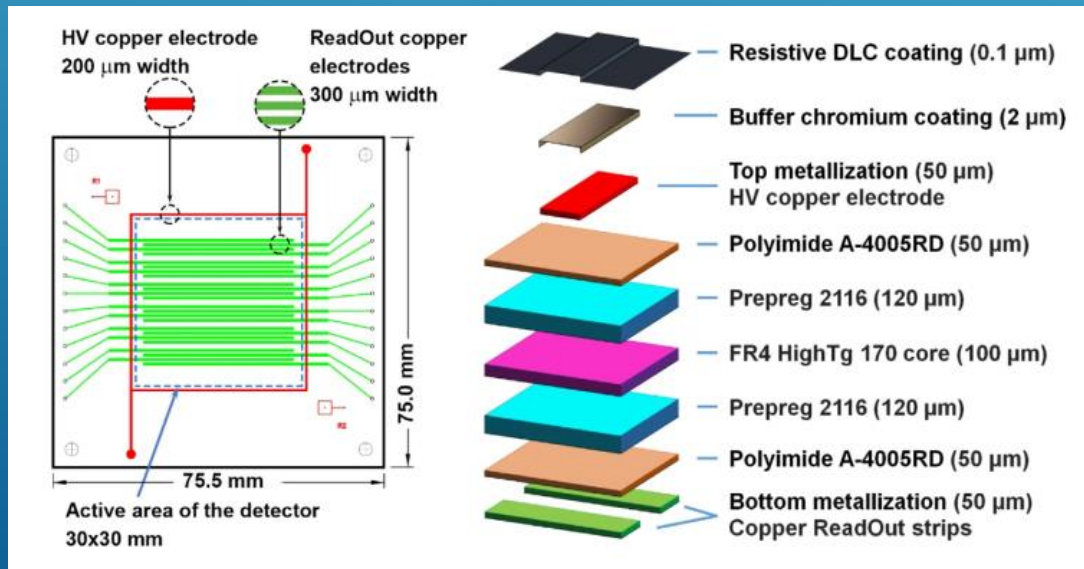
# MICROMEGAS + DLC PROTOTYPE

## Prototype cross-section



Active area:  
30x30 mm

## PCB layout and stack-up sketch



**DLC:**  
 PVD method  
 thickness – 100 nm  
 R= 30 MOhm/sq

G peak – sp<sup>3</sup> – “diamond”  
 D peak – sp<sup>2</sup> – “carbon”

“Diamond” fraction – 34%



# MICROMEGAS + DLC PROTOTYPE

## Test results

### Test setup

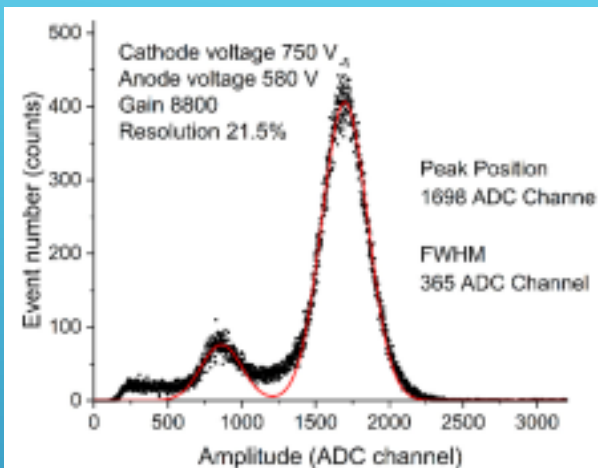
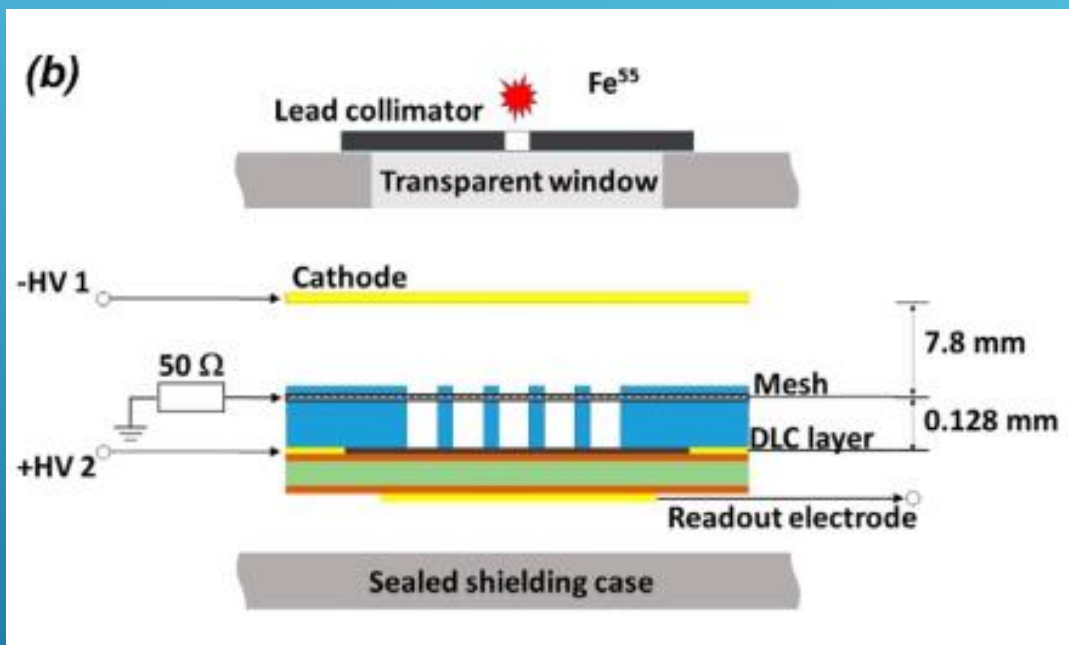


Fig. 6. Amplitude spectrum of the  $^{59}Fe$  radioactive source.

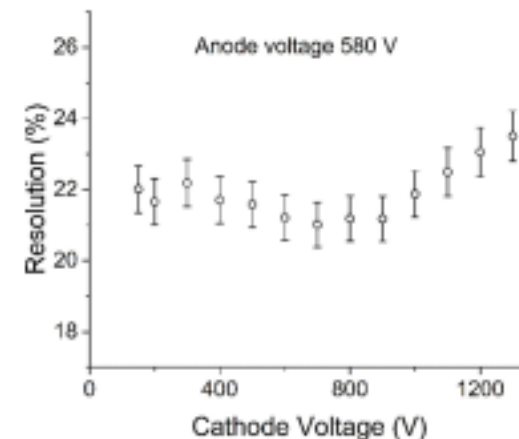


Fig. 8. The dependence of the energy resolution of the 5.9 keV peak on the cathode voltage at the fixed anode voltage of 580 V.

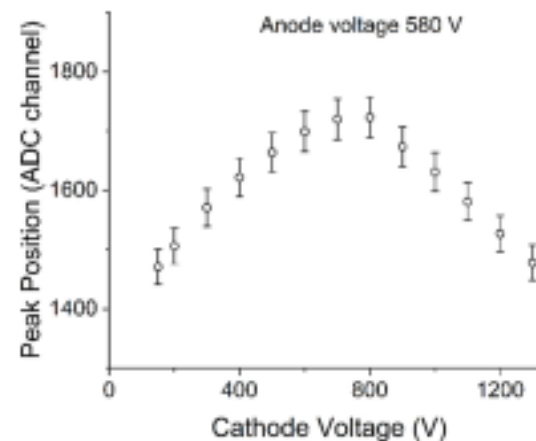


Fig. 7. The dependence of the 5.9 keV peak position on the cathode voltage at the fixed anode voltage of 580 V.

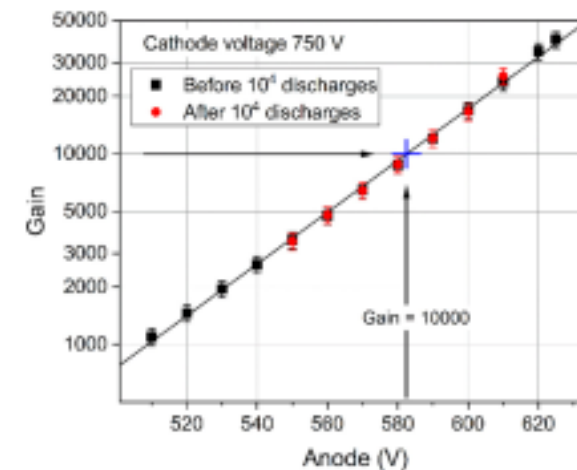


Fig. 9. The dependence of gas gain on anode voltage.

10 000 discharges – NO visible DLC degradation

## Dear colleagues!

**WELCOME** to MPD TPC upgrade program:

- minimization of **TPC End cap radiation length**:
  - new ROC chamber R&D (carbon frame, GEM, ThGEM, MicroMegas, WEM ...)
  - FE electronics (preamps on pad plane, links to FPGAs, rad hard FPGAs ...)
  - Al LV cables
- **R&D: DLC** properties study and search other resistive materials (for spark protection)
- **R&D: MPGD + DLC** prototypes and study
- manufacture of **new serial ROC chambers** (30 pc)
- upgrade TPC **gas system**

**Thank you !!!**



